

# SOT911-1

plastic thin fine-pitch ball grid array package; 56 balls; body  
4 x 4.5 x 0.8 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	TFBGA56
<b>Package type industry code</b>	TFBGA56
<b>Package style descriptive code</b>	TFBGA (thin fine-pitch ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	14-9-2005

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.4	-	4.5	4.6	mm
E	package width	3.9	-	4	4.1	mm
A	seated height	[tbd]	-	1.2	1.2	mm
A <sub>2</sub>	package height	0.75	-	0.8	0.9	mm
n <sub>2</sub>	actual quantity of termination	-	-	56	-	



2. Package outline

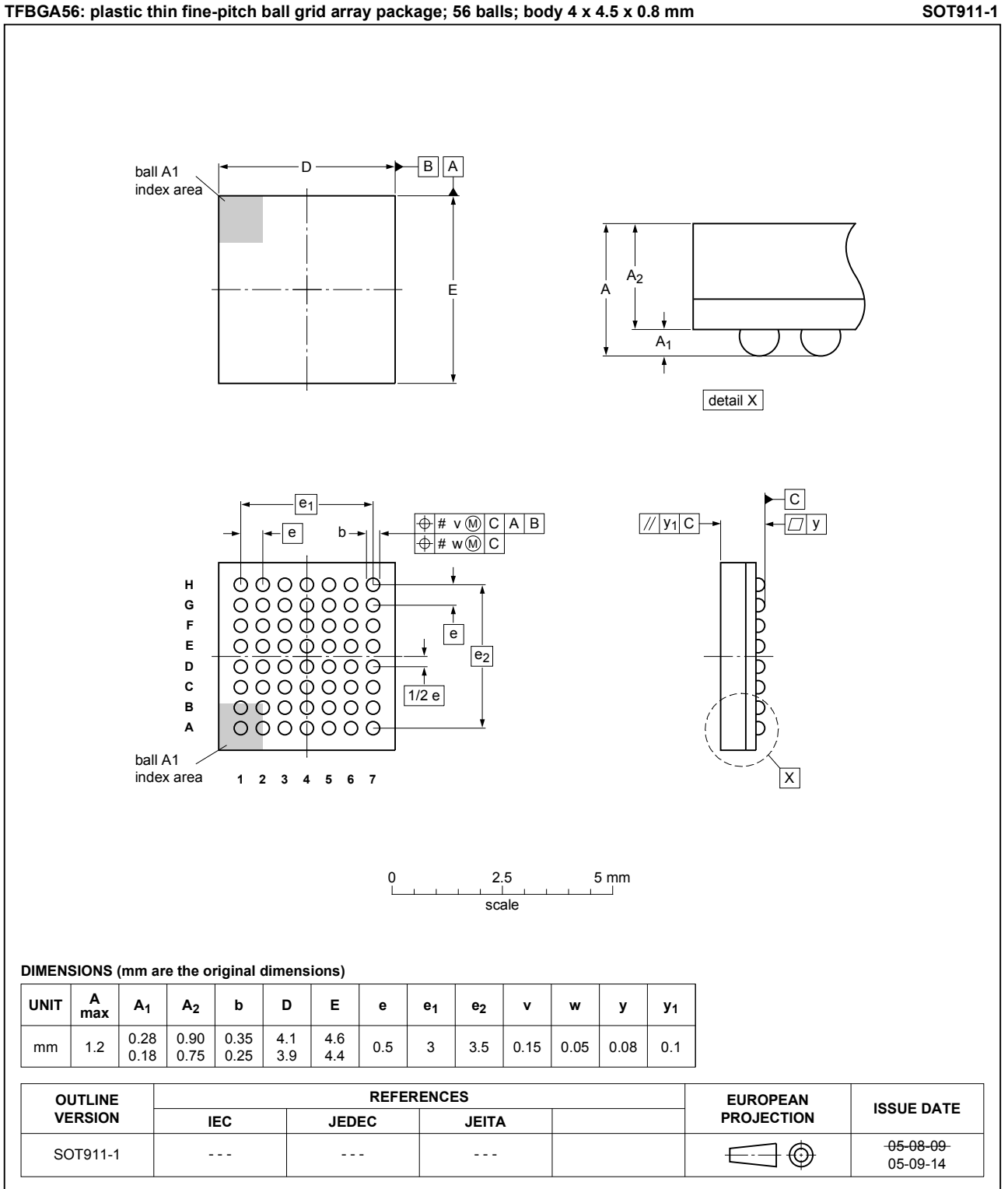


Fig. 1. Package outline TFBGA56 (SOT911-1)

### 3. Soldering

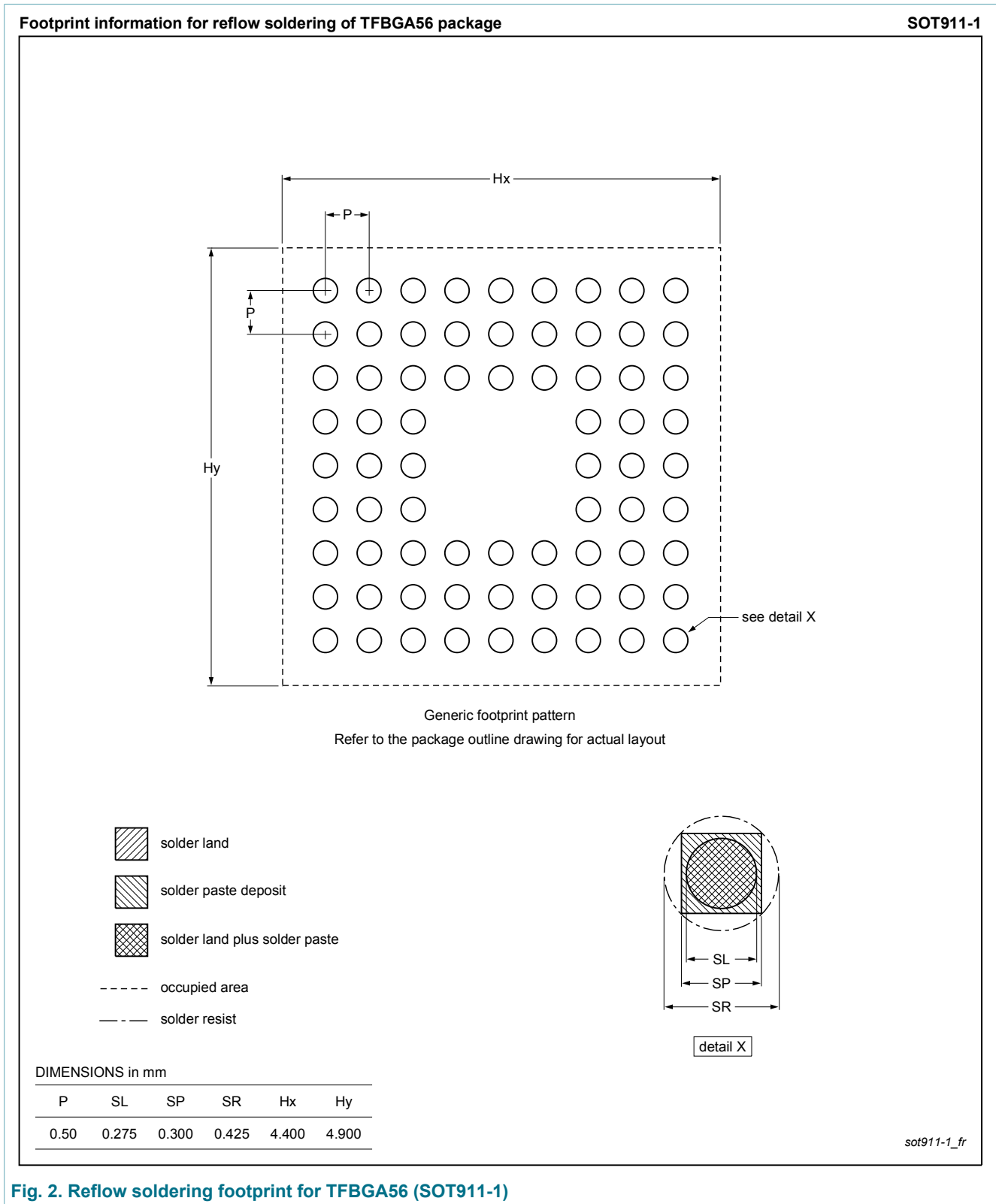


Fig. 2. Reflow soldering footprint for TFBGA56 (SOT911-1)

## 4. Legal information

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## 5. Contents

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1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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